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DATA SHEET

CBT16212

24-bit bus exchange switch
with 12-bit output enables

Product data

2001 Sep 28

File under Integrated Ciruits ICL03

Philips
Semiconductors

PHILIPS

24-bit bus exchange switch with 12-bit output enables CBT16212

FEATURES

- 5 Ω switch connection between two ports
- TTL compatible control input levels
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- ESD protection exceeds 1500 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101

DESCRIPTION

The CBT16212 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The CBT16212 operates as 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The CBT16212 is characterized for operation from –40 to +85°C.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25 °C; GND = 0 V	TYPICAL	UNIT
t_{pd}	Propagation delay An to Bn	C_L = 50 pF; V_{CC} = 5 V	0.25	ns
C_{IN}	Input capacitance	V_I = 0 V or V_{CC}	4.5	pF
C_{OUT}	Output capacitance	Outputs disabled; V_O = 0 V or V_{CC}	11.5	pF
r_{on}	A1 to A2	V_{CC} = 4.5 V; V_I = 0 V	4	Ω

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER
56-Pin Plastic SSOP	–40 to +85 °C	CBT16212DL	SOT371-1
56-Pin Plastic TSSOP	–40 to +85 °C	CBT16212DGG	SOT364-1

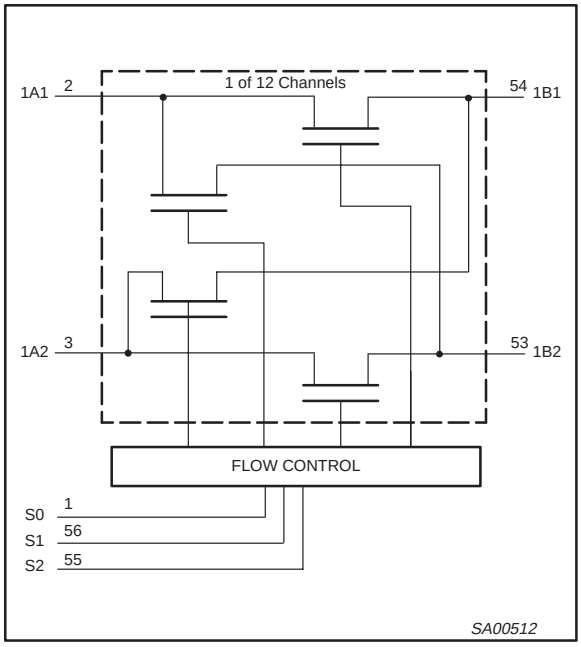
NOTE:
1. Standard packing quantities and other packaging data is available at **www.philipslogic.com/support/packages**.

FUNCTION TABLE

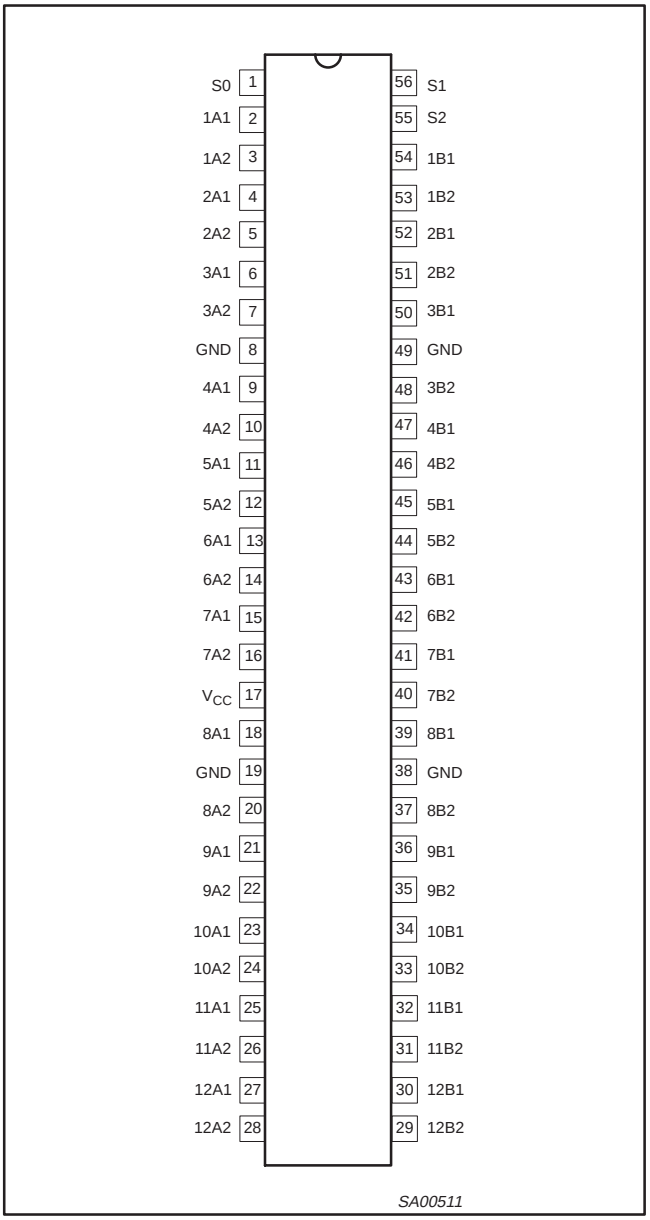
S2	S1	S0	A1	A2	FUNCTION
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 = B1
L	H	L	B2	Z	A1 = B2
L	H	H	Z	B1	A2 = B1
H	L	L	Z	B2	A2 = B2
H	L	H	Z	Z	Disconnect
H	H	L	B1	B2	A1 = B1, A2 = B2
H	H	H	B2	B1	A1 = B2, A2 = B1

H = High voltage level
L = Low voltage level
Z = High impedance “off” state

LOGIC SYMBOL



PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 56, 55	S0, S1, S2	Data select
2, 4, 6, 9, 11, 13, 15, 18, 21, 23, 25, 27	1A1–12A1	A1 channel
3, 5, 7, 10, 12, 14, 16, 20, 22, 24, 26, 28	1A2–12A2	A2 channel
54, 52, 50, 47, 45, 43, 41, 39, 36, 34, 32, 30	1B1, 12B1	B1 channel
53, 51, 48, 46, 44, 42, 40, 37, 35, 33, 31, 29	1B2, 12B2	B2 channel
8, 19, 38, 49	GND	Ground (0 V)
17	V_{CC}	Positive supply voltage

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage[3]		–0.5 to +7.0	V
V_{OUT}	DC output voltage[3]	output in Off or High state	–0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{stg}	Storage temperature range		–65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.0	5.5	V
V_{IH}	High-level input voltage	2.0	—	V
V_{IL}	Low-level Input voltage	—	0.8	V
T_{amb}	Operating free-air temperature range	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			T_{amb} = –40 to +85 °C			
			Min	Typ[1]	Max	
V_{IK}	Input clamp voltage	V_{CC} = 4.5 V; I_I = –18 mA	—	—	–1.2	V
I_I	Input leakage current	V_{CC} = 0 V; V_I = 5.5 V	—	—	10	µA
		V_{CC} = 5.5 V; V_I = GND or 5.5 V	—	—	±1	
I_{CC}	Quiescent supply current	V_{CC} = 5.5 V; I_O = 0, V_I = V_{CC} or GND	—	—	3	µA
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 5.5 V, one input at 3.4 V, other inputs at V_{CC} or GND	—	—	2.5	mA
C_I	Control pins capacitance	V_I= 3 V or 0	—	4.7	—	pF
$C_{IO(OFF)}$	Port Off capacitance	V_O = 3 V or 0; S0, S1, or S2 = V_{CC}	—	11.5	—	pF
r_{on}[3]	A1 to A2	V_{CC} = 4.0 V; V_1 = 2.4 V; I_I = 15 mA	—	—	21	Ω
		V_{CC} = 4.5 V; V_1 = 0 V; I_I = 64 mA	—	4	7	
		V_{CC} = 4.5 V; V_1 = 0 V; I_I = 30 mA	—	4	7	
		V_{CC} = 4.5 V; V_1 = 2.4 V; I_I = 15 mA	—	6	12	

NOTES:
1. All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C
2. This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.
3. Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

AC CHARACTERISTICS

GND = 0 V; t_R; C_L = 50 pF

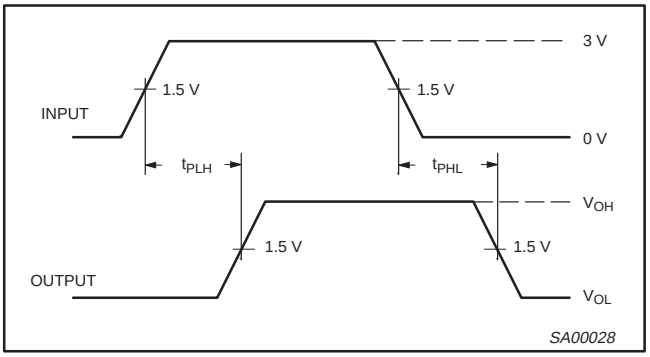
SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5.0 V ±0.5 V		UNIT
				Min	Max	
t_{pd}	Propagation delay[1]	A or B	B or A	—	0.25	ns
t_{en}	Output enable time to High and Low level	S	A or B	3.6	8.0	ns
t_{dis}	Output disable time from High and Low level	S	A or B	4.3	8.0	ns

NOTES:

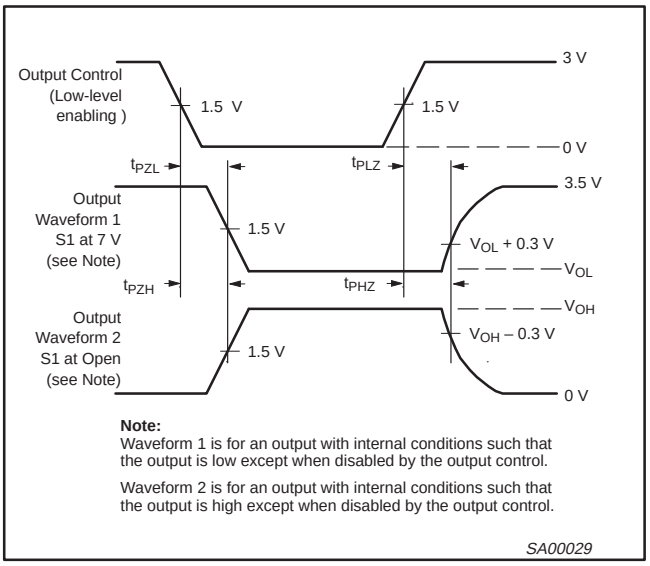
1. This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

AC WAVEFORMS

V_M = 1.5 V, V_{IN} = GND to 3.0 V

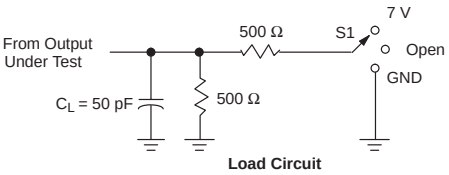


Waveform 1. Input (An) to Output (Yn) Propagation Delays


Output Control (Low-level enabling)
3 V
1.5 V
1.5 V
0 V
tPZL
tPLZ
Output Waveform 1 S1 at 7 V (see Note)
3.5 V
1.5 V
VOL + 0.3 V
VOL
tPZH
tPHZ
VOH
Output Waveform 2 S1 at Open (see Note)
VOH – 0.3 V
1.5 V
0 V
Note:
Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
SA00029

Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS



Load Circuit

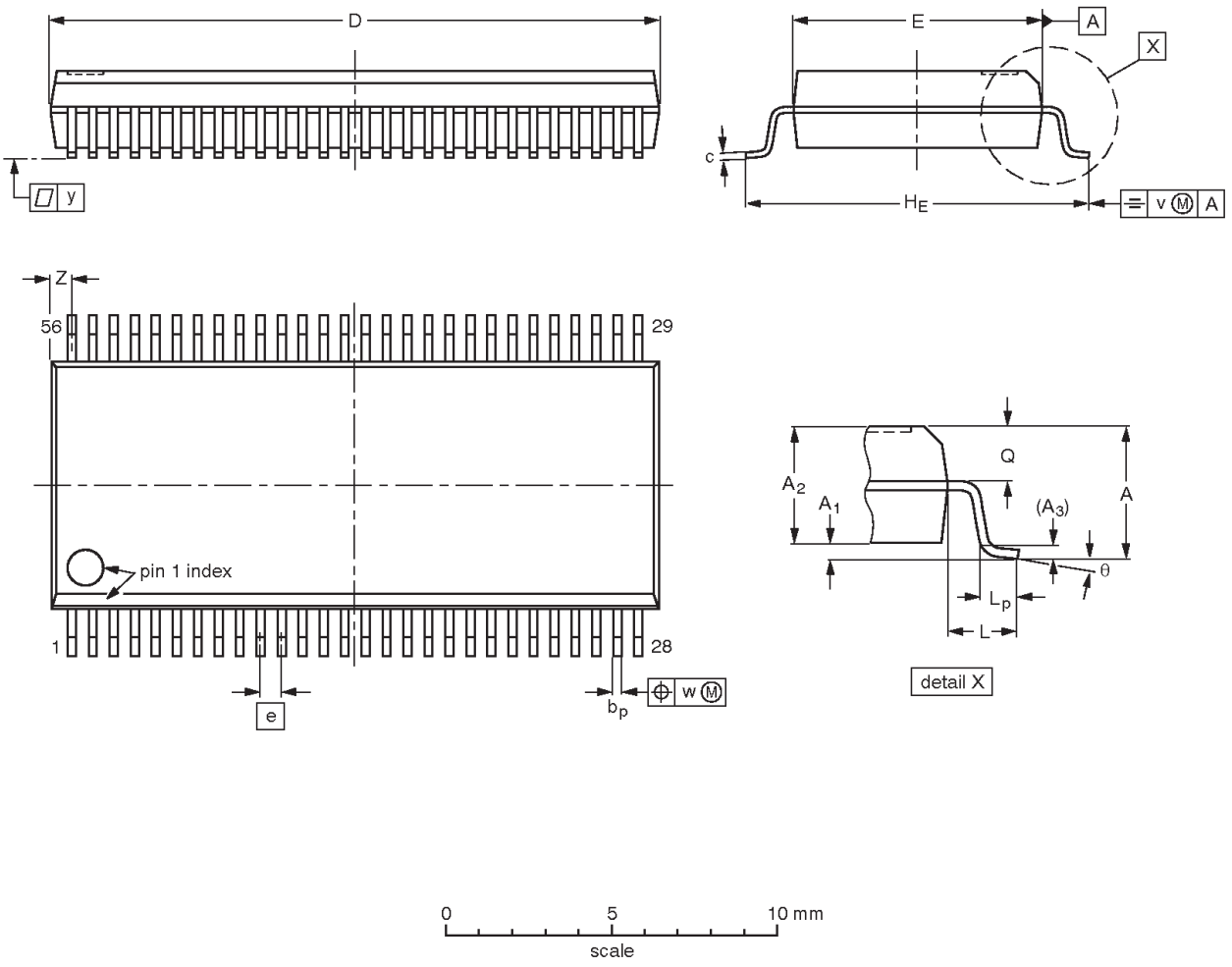
TEST	S1
t_{pd}	open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	open

DEFINITIONS

C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

SA00012

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm **SOT371-1**



DIMENSIONS (mm are the original dimensions)

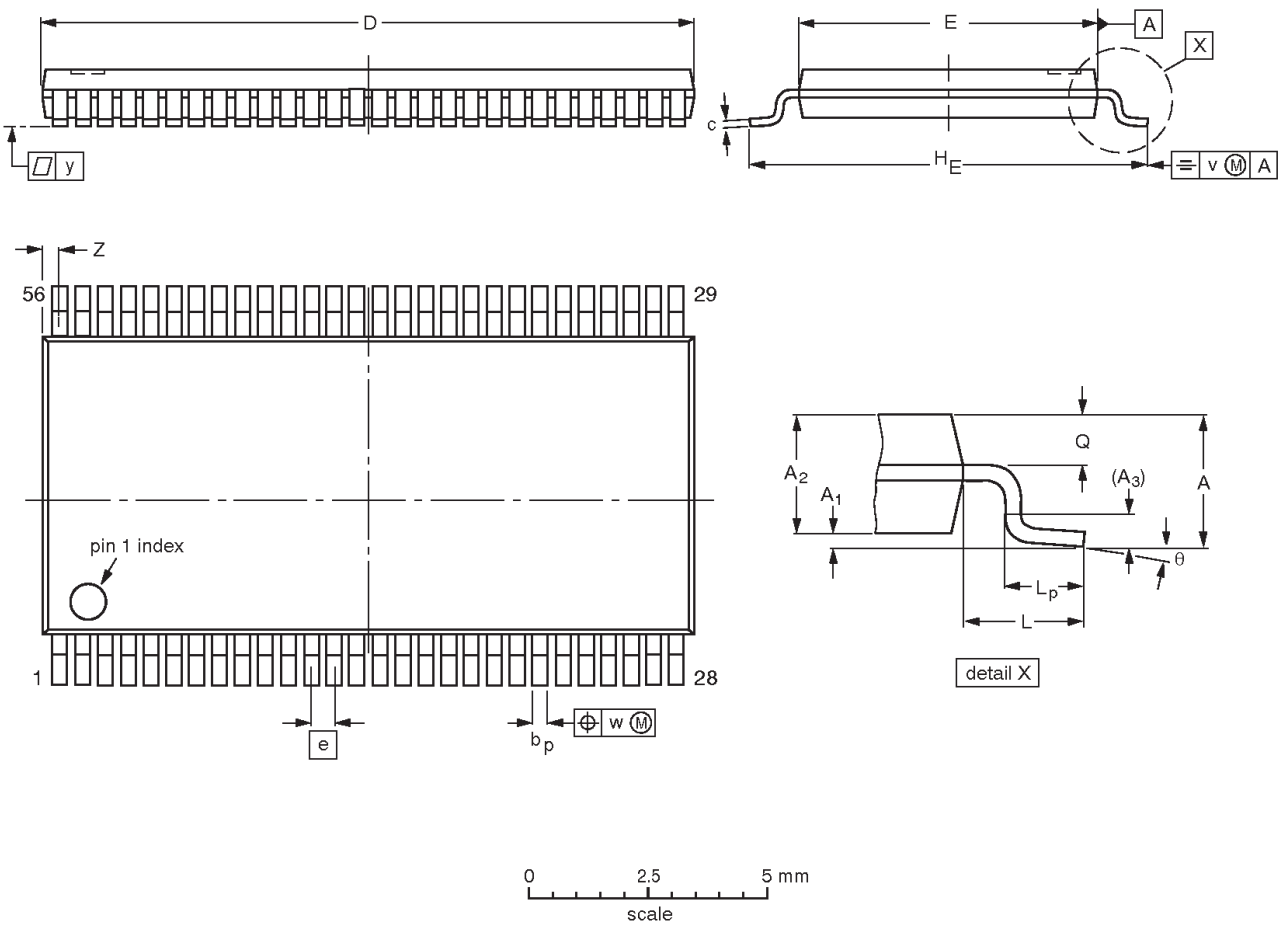
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT371-1		MO-118				~~95-02-04~~ 99-12-27

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm **SOT364-1**



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT364-1		MO-153					~~95-02-10~~ 99-12-27

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Data sheet status [1]	Product status [2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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